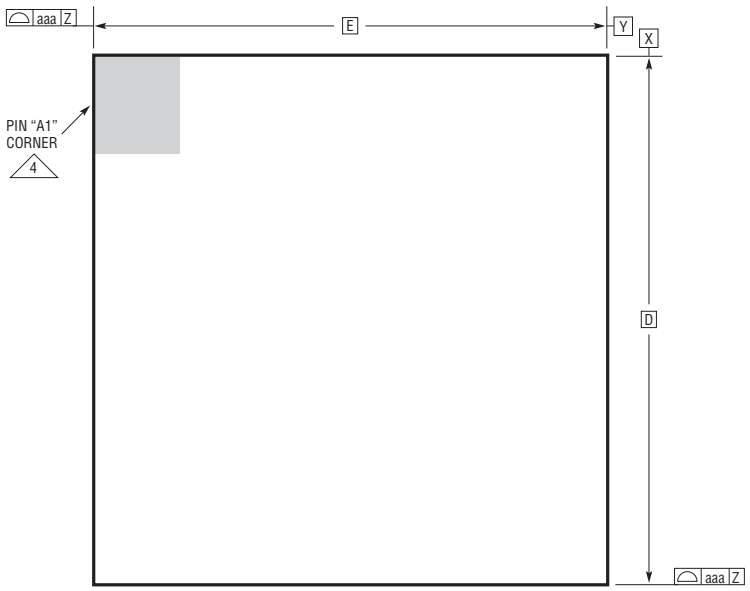
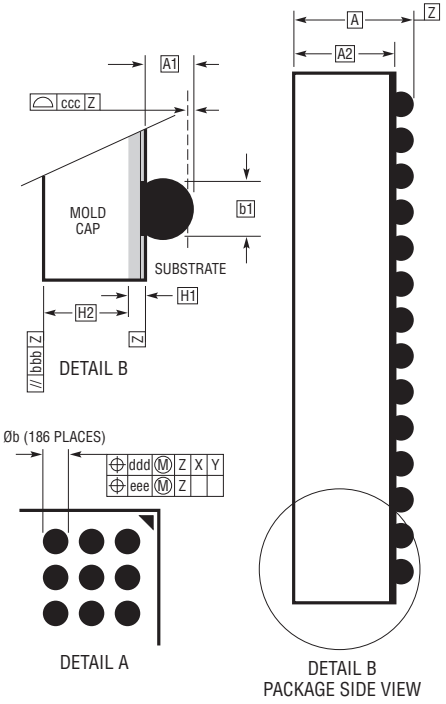
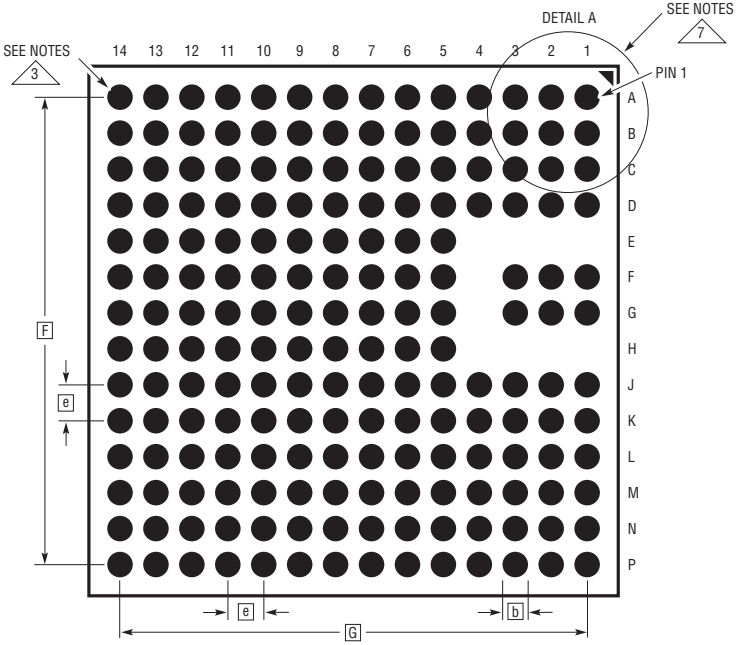
BGA Package
186-Lead (15mm × 15mm × 3.32mm)
(Reference LTC DWG# 05-08-1670 Rev Ø)

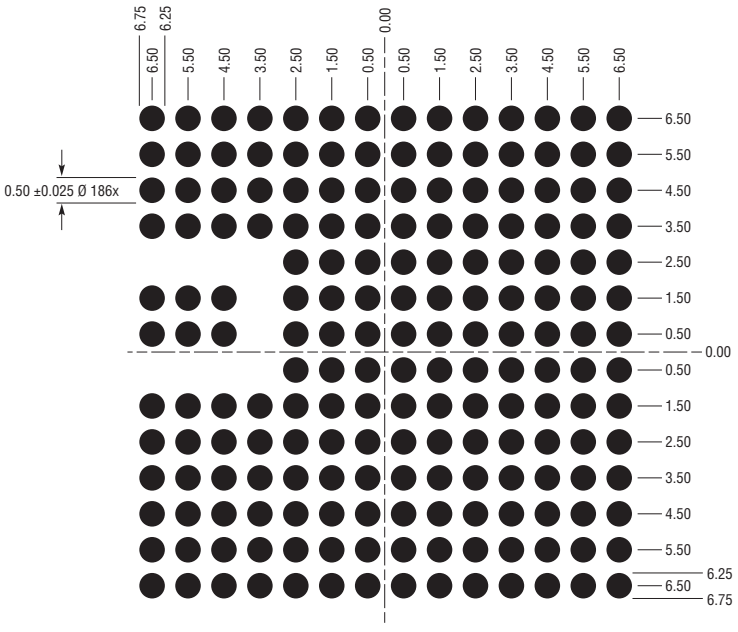


PACKAGE TOP VIEW





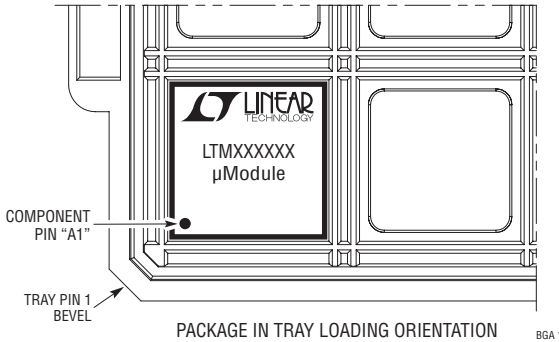
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.12	3.32	3.52	
A1	0.40	0.50	0.60	
A2	2.72	2.82	2.92	
b	0.50	0.60	0.70	
b1	0.47	0.50	0.53	
D		15.0		
E		15.0		
e		1.0		
F		13.0		
G		13.0		
H1	0.27	0.32	0.37	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	
TOTAL NUMBER OF BALLS: 186				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 186 0215 REV Ø